SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SR1011□□□□L□-□□□		
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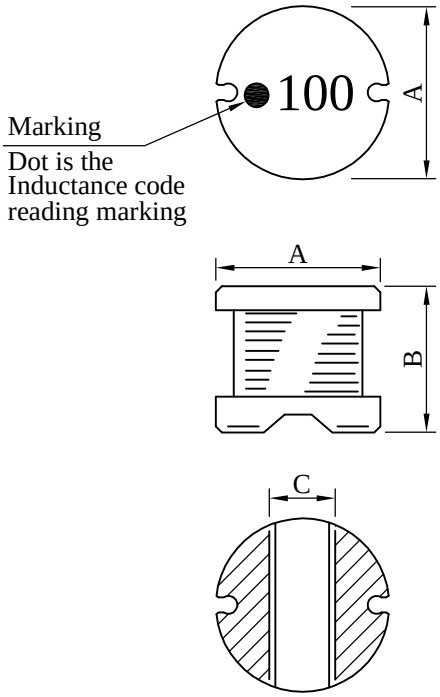
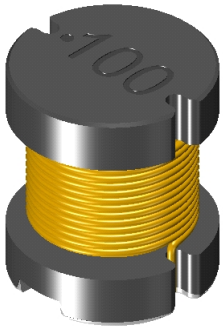
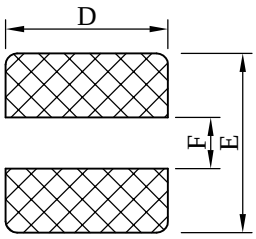
Ⅰ．Configuration and dimensions：







(PCB Pattern)

Unit：m/m

A	B	C	D	E	F
9.50 ±0.3	11.50 ±0.5	2.90 ref.	10.0 ref.	10.0 ref.	2.80 ref.

Ⅱ．Description：

a．Ferrite drum core construction.

b．Enamelled copper wire：H class

c．Product weight： 3.20 g（ref.）

d．Moisture sensitivity Level 1

e．Products comply with RoHS' requirements

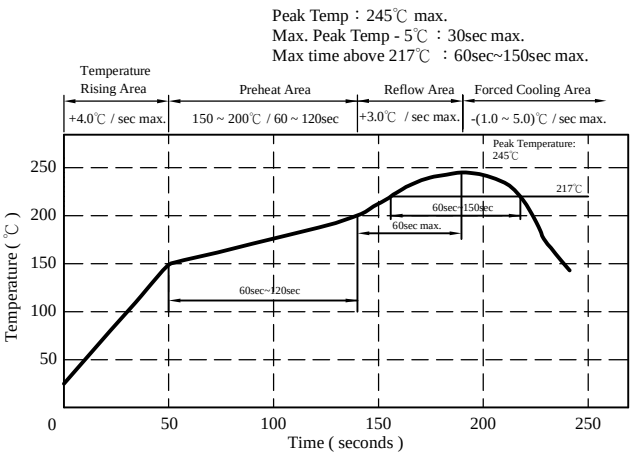
f．Halogen free available

Ⅲ．General specification：

a．Storage temp.：-40℃ ----+125℃

b．Operating temp.：-40℃----+125℃
(Temp. rise included)

c．Resistance to solder heat：245℃.10 secs.



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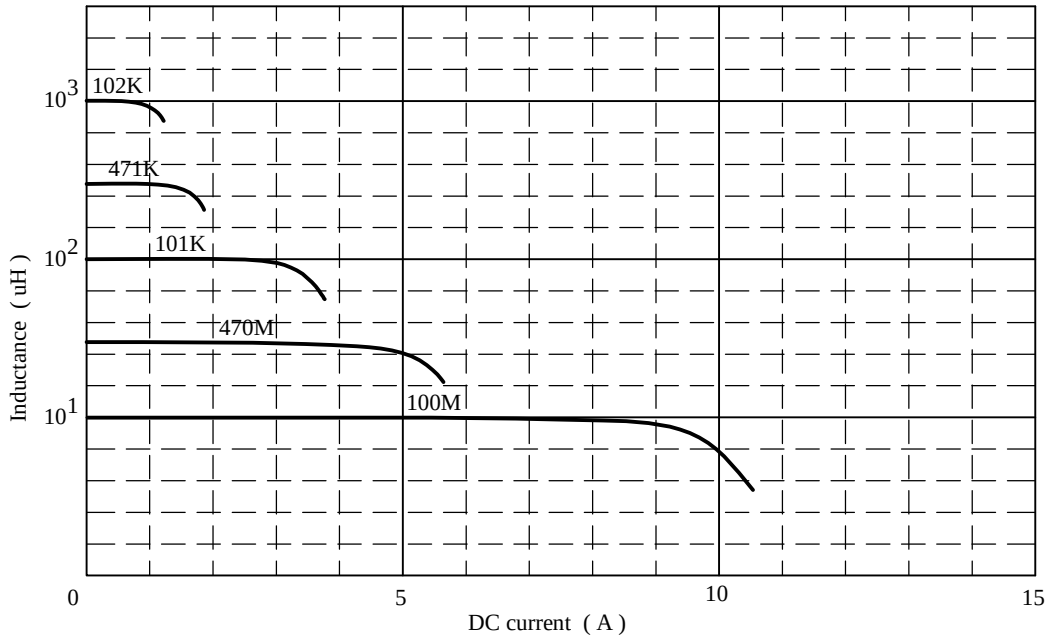
Ⅳ . Electrical characteristics：

DWG No.	Inductance (μH)	SRF (MHz) typ.	RDC (Ω) max.	Irms 1 (A) typ.	Irms 2 (A) max.	Isat (A) max.
SR1011100ML□-□□□	10.0 ± 20%	18.0	0.035	3.50	5.00	8.00
SR1011150ML□-□□□	15.0 ± 20%	13.0	0.045	3.00	4.00	7.00
SR1011220ML□-□□□	22.0 ± 20%	12.0	0.065	2.50	3.20	5.50
SR1011330ML□-□□□	33.0 ± 20%	9.5	0.080	2.00	2.60	4.00
SR1011470ML□-□□□	47.0 ± 20%	7.0	0.110	1.70	2.20	3.80
SR1011680ML□-□□□	68.0 ± 20%	5.8	0.150	1.50	2.00	3.00
SR1011101KL□-□□□	100.0 ± 10%	4.8	0.200	1.30	1.80	2.50
SR1011151KL□-□□□	150.0 ± 10%	3.8	0.320	1.00	1.50	2.00
SR1011221KL□-□□□	220.0 ± 10%	3.1	0.420	0.90	1.20	1.70
SR1011331KL□-□□□	330.0 ± 10%	2.5	0.700	0.70	0.90	1.30
SR1011471KL□-□□□	470.0 ± 10%	2.1	0.900	0.50	0.75	1.10
SR1011681KL□-□□□	680.0 ± 10%	1.7	1.250	0.40	0.60	1.00
SR1011102KL□-□□□	1000.0 ± 10%	1.4	1.900	0.30	0.50	0.80

1). □：Packaging information：□ Code
2). "-□□□ "：Reference code
3). Electrical specifications at 25℃
4). Test Freq：100kHz , 0.1V
5). Isat base on △L/L0A=10% max.
6). Irms 1 base on temp. rise 20℃ typ.
7). Irms 2 base on temp. rise 40℃ max.

@ Inductance VS. DC superposition characteristics



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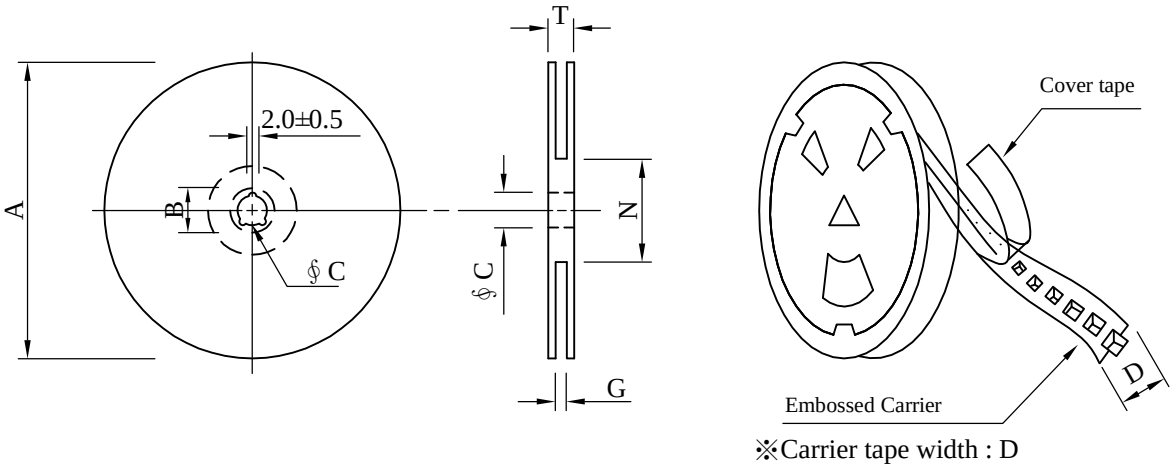
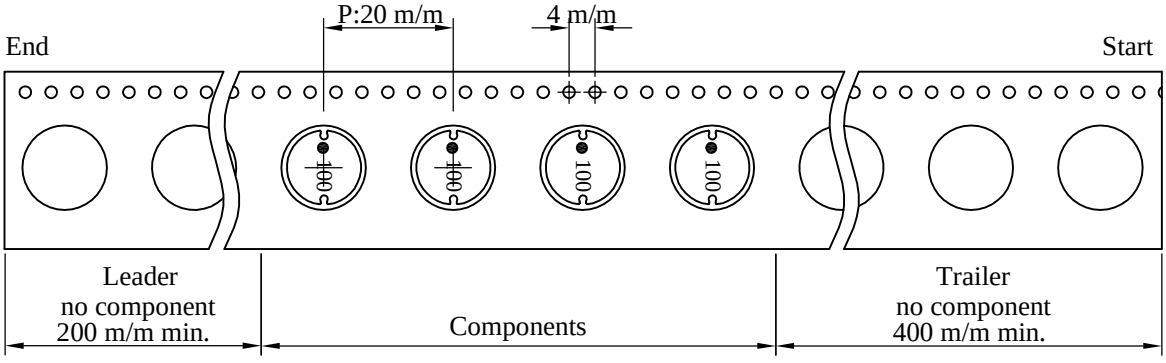
V ．Packaging information：

(1) Configuration



※Carrier tape width : D



User direction of feed

(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 24	330	21±0.8	13±0.5	24	26^{+0}	60^{-0}	30.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	250	1320	13 - 24	1,000	6.6	38 x 37 x 22

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Ⅵ．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature：85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperarance. 2.No marking blurred. 3.Inductance shall not change more than ±10%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature：245±5℃. 2.Time（temp.≧ 217℃）：60~150 Second. 3.IR reflow times：3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 10% max.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ max.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing： 150±5℃ / 16Hours±30 min. 2.Peak temperature：240±5℃ 3.Time（temp.≧217℃）：60~150 second. 4.IR reflow times：1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature：-40℃~125℃ 2.Room temperature：25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. pcb and dropped down from a heigh of 1m 2.Drop total time：6 time (Every side ofsample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.